WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

a semiconductor chip having bumps on its surface and a chip-mounting member having internal terminals on its chip-mounting face while having external terminals on its external connection face and constituted by bonding the bumps on the semiconductor chip to internal terminals of the chip-mounting member while turning the semiconductor chip upside down, wherein

the external terminals are formed in areas corresponding to arrangement areas of the internal terminals at the both sides of the chip-mounting member.

2. A semiconductor device comprising:

a semiconductor chip having bumps on its surface and a chip-mounting member having internal terminals on its chip-mounting face while having external terminals on its external connection face and constituted by bonding the bumps on the semiconductor chip to internal terminals of the chip-mounting member while turning the semiconductor chip upside down, wherein

the external terminals are formed outside of areas corresponding to arrangement areas of the internal terminals at the both sides of the chip-mounting member.

3. The semiconductor device according to claim 1, wherein dummy terminals are formed outside of arrangement areas of the external terminals on the external connection face of the chip-mounting member but inside of areas corresponding to arrangement areas of the internal terminals at the both sides of the chip-mounting member.

Cont Sub A'

4. A semiconductor device comprising:

a semiconductor chip having bumps on its surface and a chip-mounting member having a plurality of internal terminals with heights different from each other on its chip-mounting face and constituted by bonding the bumps on the semiconductor chip to the internal terminals of the chip-mounting member while turning the semiconductor chip upside down, wherein

heights of the bumps are changed in accordance with heights of the internal terminals so that the chip-mounting member and the semiconductor chip are parallel with each other.

5. The semiconductor device according to claim 4, wherein heights of the bumps are changed in accordance with the overlapped number of the bumps.

Cont Sub A'

6. The semiconductor device according to claim 4, wherein the chip-mounting member is a multilayer substrate having a plurality of wiring layers and the internal terminals on the wiring layers.

7. The semiconductor device according to claim 4, wherein the chip-mounting member is a chip-mounting-type semiconductor chip having a plurality of wiring layers and the internal terminals on the wiring layers.